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Additive Manufacturing: Recent Advances, Applications and Challenges

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Message from the Guest Editor

Predictions for the fourth industrial revolution, "Industry 4.0", are that additive manufacturing technologies capable of replacing conventional manufacturing processes will be able to produce one component/ part as economically and efficiently as possible in mass production.

The evolution of industries depends not only on innovative and cutting-edge research activities associated with materials, manufacturing processes, and performance control means, but also on the research of new additive manufacturing process types, innovative simulation methods, more diverse application scenarios, and the mining of product structure design.

Subjects that will be discussed in this Special Issue will focus not only on material systems, manufacturing process optimization, post-processing, and physicochemical characterization, but also on the exploration of new technologies, multi-scale simulation, the fabrication of dense components with special complex structures, and potential industrial applications.











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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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